



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	02/24/2015
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7AD1*258TNC1	A	SH1A	02/24/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2,10.5,1.27	3	gull wing	
Comment	Package:D2PAK CLIP; MD valid for TN2540-800G-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices

QueryList : REACH-17th December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7AD1*258TNC1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	11.492	mg	supplier	die	Silicon (Si)	7440-21-3		10.221	mg	889401	7407
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.13	mg	11312	94
die (s)				supplier	metallization	Gold (Au)	7440-57-5		0.028	mg	2436	20
die (s)				supplier	passivation	Alumina	1344-28-1		0.0823	mg	7162	60
die (s)				supplier	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and e	0.7407	mg	64454	537
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.013	mg	1131	9
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.277	mg	24104	201
Leadframe	Copper & its alloys	904.122	mg	supplier	alloy	Copper (Cu)	7440-50-8		903.218	mg	999000	654506
Leadframe				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.904	mg	1000	655
Soft solder	Solder	7.722	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	7.143	mg	925019	5176
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.193	mg	24994	140
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.386	mg	49987	280
Bonding wire	Other inorganic materials	71.018	mg	supplier	wire	Copper (Cu)	7440-50-8		71.018	mg	1000000	51462
encapsulation	Other Organic Materials	379.332	mg	supplier	mold compound	Silica, vitreous	60676-86-0		288.293	mg	760002	208908
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		22.76	mg	60000	16493
encapsulation				supplier	mold compound	Carbon black	1333-86-4		3.034	mg	7998	2199
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		38.692	mg	102000	28038
encapsulation				supplier	mold compound	Metal hydroxide	Proprietary		7.586	mg	19998	5497
encapsulation				supplier	mold compound	Others	Proprietary		18.967	mg	50001	13744
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575